

Title (en)

ION BEAM-ASSISTED HIGH-TEMPERATURE SUPERCONDUCTOR (HTS) DEPOSITION FOR THICK FILM TAPE

Title (de)

IONENSTRÄHLUNTERSTÜTZTE HOCHTEMPERATURSUPRALEITUNGS- (HTS-)ABSCHIEDUNG FÜR DICKES FOLIENBAND

Title (fr)

DEPOT SUR SUPRACONDUCTEUR HAUTE TEMPERATURE CRITIQUE ASSISTE PAR FAISCEAU IONIQUE POUR BANDE A FILM EPAIS

Publication

**EP 1638701 A4 20070221 (EN)**

Application

**EP 04776126 A 20040525**

Priority

- US 2004016597 W 20040525
- US 45673303 A 20030605

Abstract (en)

[origin: US2004247780A1] An ion source impinging on the surface of the substrate to be coated is used to enhance a MOCVD, PVD or other process for the preparation of superconducting materials.

IPC 8 full level

**C23C 14/08** (2006.01); **C23C 14/22** (2006.01); **C23C 14/28** (2006.01); **C23C 16/40** (2006.01); **C23C 16/48** (2006.01); **H01L 39/24** (2006.01)

CPC (source: EP KR US)

**C23C 14/08** (2013.01 - KR); **C23C 14/087** (2013.01 - EP US); **C23C 14/14** (2013.01 - KR); **C23C 14/22** (2013.01 - EP US);  
**C23C 14/26** (2013.01 - KR); **C23C 14/28** (2013.01 - EP US); **C23C 14/46** (2013.01 - KR); **C23C 16/408** (2013.01 - EP KR US);  
**C23C 16/486** (2013.01 - EP KR US); **H10N 60/0464** (2023.02 - EP KR US); **H10N 60/0521** (2023.02 - EP KR US)

Citation (search report)

- [X] WO 9503938 A1 19950209 - HARVARD COLLEGE [US], et al
- [X] US 5650378 A 19970722 - IIJIMA YASUHIRO [JP], et al
- See references of WO 2005007918A2

Citation (examination)

- WO 02095084 A1 20021128 - COMMW SCIENT IND RES ORG [AU], et al
- US 5236509 A 19930817 - SIOSHANSI PIRAN [US], et al

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

**US 2004247780 A1 20041209; US 8182862 B2 20120522;** CA 2527870 A1 20050127; CN 100450646 C 20090114; CN 1798617 A 20060705;  
EP 1638701 A2 20060329; EP 1638701 A4 20070221; JP 2007525788 A 20070906; KR 20060021877 A 20060308;  
WO 2005007918 A2 20050127; WO 2005007918 A3 20050630

DOCDB simple family (application)

**US 45673303 A 20030605;** CA 2527870 A 20040525; CN 200480015467 A 20040525; EP 04776126 A 20040525; JP 2006514975 A 20040525;  
KR 20057023345 A 20051205; US 2004016597 W 20040525